

Description

The μPB10474 is a very high-speed 10K interface ECL RAM organized as 1,024 words by 4 bits and designed with noninverted, open-emitter outputs and low power consumption. Three versions with access times of 8 ns, 10 ns and 15 ns maximum are available in hermetic, 400-mil, 24-pin cerdip packaging.

Features

- 1,024-word x 4-bit organization
- 10K ECL interface
- Noninverted, open-emitter outputs
- Fast access times
- Low power consumption
- 400-mil, 24-pin cerdip packaging

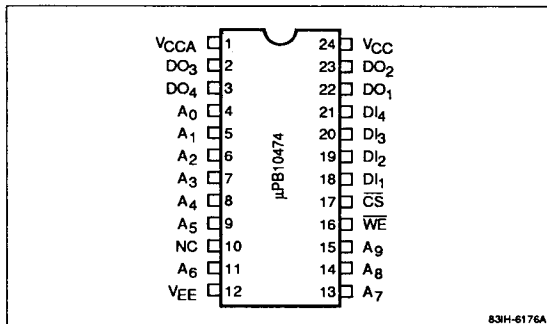
Ordering Information

Part Number	Access Time (max)	Package
μPB10474D-8	8 ns	24-pin cerdip
D-10	10 ns	
D-15	15 ns	

Pin Configuration

24-Pin Cerdip

25c



Pin Identification

Symbol	Function
A ₀ - A ₉	Address inputs
DI ₁ - DI ₄	Data inputs
DO ₁ - DO ₄	Data outputs
WE	Write enable
CS	Chip select
VCC	Power supply (current switches and bias driver)
VCCA	Power supply (output devices)
VEE	Power supply
NC	No connection

Absolute Maximum Ratings

Supply voltage, V_{EE} to V_{CC}	-7.0 to +0.5 V
Input voltage, V_{IN}	V_{EE} to +0.5 V
Output current, I_{OUT}	-30 to +0.1 mA
Storage temperature, T_{STG}	-65 to +150°C
Storage temperature under bias, T_{STG} (bias)	-55 to +125°C

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Truth Table

\overline{CS}	\overline{WE}	D_{IN}	Output	Mode
H	X	X	L	Not selected
L	L	L	L	Write 0
L	L	H	L	Write 1
L	H	X	D_{OUT}	Read

Notes:

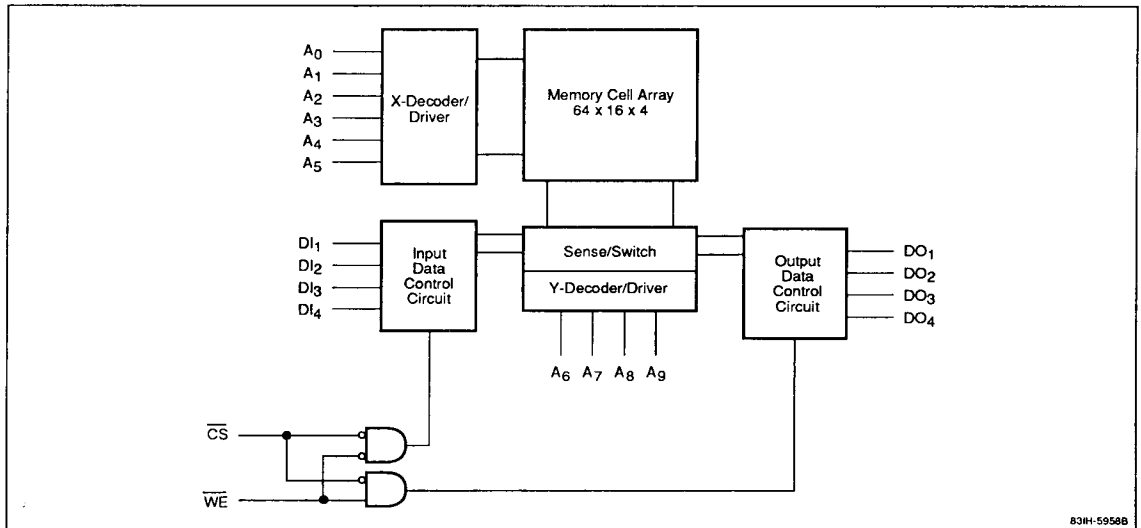
(1) X = don't care.

Capacitance

f = 1 MHz

Parameter	Symbol	Min	Typ	Max	Unit
Input capacitance	C_{IN}		4		pF
Output capacitance	C_{OUT}		5		pF

Block Diagram



DC Characteristics

$T_A = 0$ to $+75^\circ\text{C}$; $V_{EE} = -5.2\text{ V}$; output load = $50\ \Omega$ to -2.0 V

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Output voltage, high	V_{OH}	-1000		-840	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 0^\circ\text{C}$
		-960		-810	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 25^\circ\text{C}$
		-900		-720	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 75^\circ\text{C}$
Output voltage, low	V_{OL}	-1870		-1665	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 0^\circ\text{C}$
		-1850		-1650	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 25^\circ\text{C}$
		-1830		-1625	mV	$V_{IN} = V_{IH}$ max or V_{IL} min; $T_A = 75^\circ\text{C}$
Output threshold voltage, high	V_{OHC}	-1020			mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 0^\circ\text{C}$
		-980			mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 25^\circ\text{C}$
		-920			mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 75^\circ\text{C}$
Output threshold voltage, low	V_{OLC}			-1645	mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 0^\circ\text{C}$
				-1630	mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 25^\circ\text{C}$
				-1605	mV	$V_{IN} = V_{IH}$ min or V_{IL} max; $T_A = 75^\circ\text{C}$
Input voltage, high	V_{IH}	-1145		-840	mV	For all inputs: $T_A = 0^\circ\text{C}$
		-1105		-810	mV	For all inputs: $T_A = 25^\circ\text{C}$
		-1045		-720	mV	For all inputs: $T_A = 75^\circ\text{C}$
Input voltage, low	V_{IL}	-1870		-1490	mV	For all inputs: $T_A = 0^\circ\text{C}$
		-1850		-1475	mV	For all inputs: $T_A = 25^\circ\text{C}$
		-1830		-1450	mV	For all inputs: $T_A = 75^\circ\text{C}$
Input current, high	I_{IH}			220	μA	$V_{IN} = V_{IH}$ max
Input current, low	I_{IL}	0.5		170	μA	For CS: $V_{IN} = V_{IL}$ min
		-50			μA	For all others: $V_{IN} = V_{IL}$ min
Supply current	I_{EE}	-220			mA	All inputs and outputs open

Notes:

- (1) The device under test is mounted in a test socket and measured at a thermal equilibrium established with a transverse air flow maintained at greater than 2.0 m/s.

25c

AC Characteristics

$T_A = 0$ to $+75^\circ\text{C}$; $V_{EE} = -5.2\text{ V} \pm 5\%$; output load = $50\ \Omega$ to -2.0 V

Parameter	Symbol	μPB10474-8			μPB10474-10			μPB10474-15			Unit	Test Conditions
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
Read Operation												
Chip select access time	t_{ACS}			5			6			8	ns	
Chip select recovery time	t_{RCS}			5			6			8	ns	
Address access time	t_{AA}			8			10			15	ns	
Write Operation												
Write pulse width	t_W	6			10			15			ns	
Data setup time	t_{WSD}	1			2			2			ns	
Data hold time	t_{WHD}	1			2			2			ns	
Address setup time	t_{WSA}	1			3			3			ns	
Address hold time	t_{WHA}	1			2			2			ns	
Chip select setup time	t_{WSCS}	1			2			2			ns	
Chip select hold time	t_{WHCS}	1			2			2			ns	
Write disable time	t_{WS}			5			6			8	ns	
Write recovery time	t_{WR}			8			10			10	ns	
Output Rise and Fall Times												
Output rise time	t_R		2			2			2		ns	
Output fall time	t_F		2			2			2		ns	

Notes:

- (1) The device under test is mounted in a test socket and measured at a thermal equilibrium established with a transverse air flow maintained at greater than 2.0 m/s.
- (2) See figures 1 and 2 for loading conditions and input pulse timing. Input pulse levels = -1.7 to -0.9 V ; input rise and fall times (measured between 20% and 80% or 80% and 20%) = 2 ns; input and output timing reference levels = 50%.

Figure 1. Loading Conditions Test Circuit

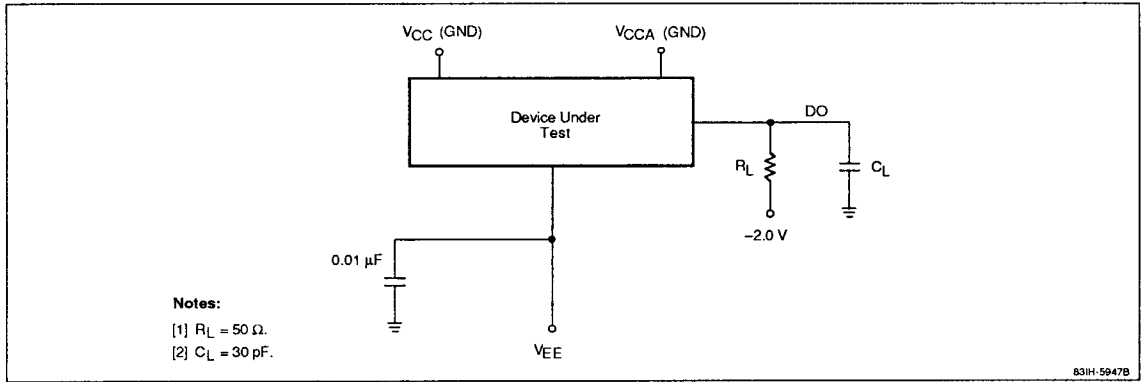
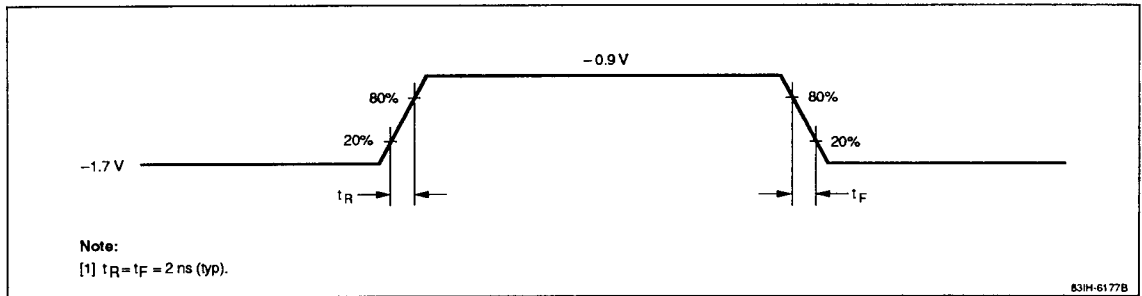
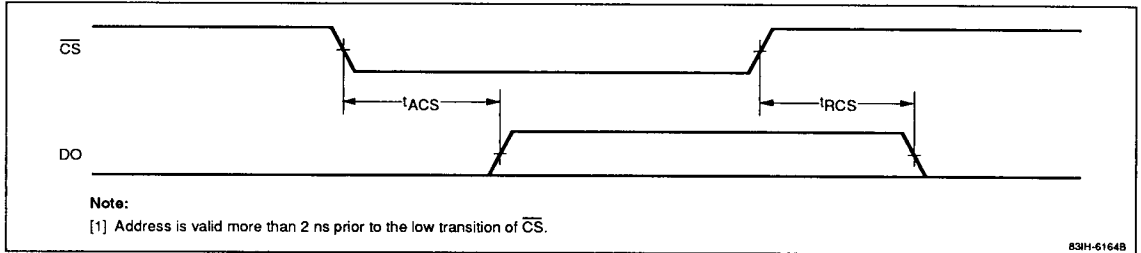


Figure 2. Input Pulse

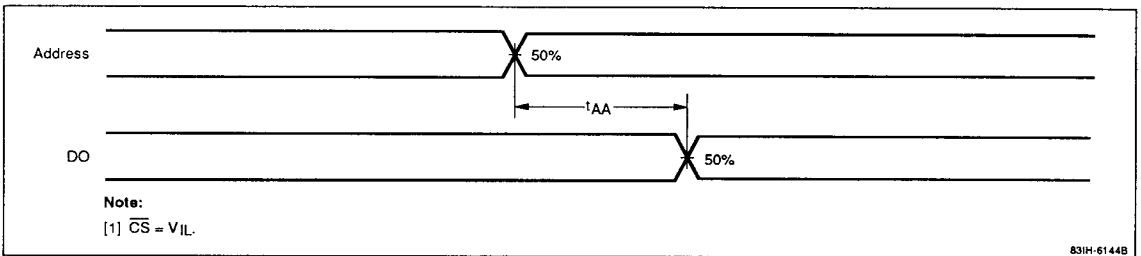


Timing Waveforms

Chip Select Access Cycle



Address Access Cycle



Write Cycle

